

ioShield-L Ver1.0 Partlist

Item	Q.ty	Reference	Part	Tech. Characteristics	Package	Assembly
1	1	C2	0.1uF	50V-10% Ceramic	CASE 0603	Top side
2	1	J1	HEADER SOCKET 8, Female	2.54mm 8X1 HEADER SOCKET, Female	2.54mm Female	Top side
3	1	J2	HEADER SOCKET 6, Female	2.54mm 6X1 HEADER SOCKET, Female	2.54mm Female	Top side
4	2	J3, J4	HEADER SOCKET 10, Female	2.54mm 10X1 HEADER SOCKET, Female	2.54mm Female	Bottom side
5	1	J5	HEADER SOCKET 3, Female	2.54mm 3X1 HEADER SOCKET, Female	2.54mm Female	Bottom side
6	1	J7	7MSDP-B0-1012	Micro SD Connector	SMD	Top side
7	2	R4,R5	10K	1/10W-5% SMD	CASE 0603	Top side
8	1	R3	0R	1/10W-5% SMD	CASE 0603	Top side
9	1	SW1	SKHMPSE010	Tact Switch 6.2X6.5 SMD	Tact Switch 6.2X6.5 SMD	Top side
10	1	U2	23K640	SPI SRAM	SOIC 8	Top side
11	1	C1	not mounted(0.1uF)	50V-10% Ceramic	CASE 0603	
12	2	C3, C4	not mounted(10uF/16V)	10uF/16V-20% Tantal	Size A	
13	1	D1	not mounted(CHIP-LED)	RED	CASE 0603	
14	1	J6	not mounted(DC JACK)	DC POWER JACK, 2PI	DC JACK	
15	1	R1	not mounted(10K)	1/10W-5% SMD	CASE 0603	
16	1	R2	not mounted(0R)	1/10W-5% SMD	CASE 0603	
17	1	R6	not mounted(330R)	1/10W-5% SMD	CASE 0603	
18	1	U1	not mounted(SN74LVC1G08)	Single AND Gate	SOT-23-5(DBV)	
19	1	U3	not mounted(GL1117-3.3)	3.3V LDO	SOT-223	
20	1		PCB	66.04mm X 50.8mm, 2Layer		